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- Qualified for Automotive Applications
- ESD Protection Exceeds 200 V Using Machine Model (C = 200 pF, R = 0)
- 100-μA Typical Starting Supply Current
- 500-µA Typical Operating Supply Current
- Operation to 1 MHz
- Internal Soft Start
- Internal Fault Soft Start

#### Internal Leading-Edge Blanking of the Current Sense Signal

- 1-A Totem-Pole Output
- 70-ns Typical Response From Current-Sense to Gate Drive Output
- 1.5% Tolerance Voltage Reference
- Same Pinout as UC3802, UC3842, and UC3842A

### description

The UCC2813-0/-1/-2/-3/-4/-5 family of high-speed low-power integrated circuits contain all of the control and drive components required for off-line and dc-to-dc fixed-frequency current-mode switching power supplies with minimal parts count.

These devices have the same pin configuration as the UC2842/3/4/5 family and also offer the added features of internal full-cycle soft start and internal leading-edge blanking of the current-sense input.

The UCC2813-0/-1/-2/-3/-4/-5 family offers choice of maximum duty cycle and critical voltage levels. Lower reference parts, such as the UCC2813-3 and UCC2813-5, fit best into battery-operated systems, while the higher reference and the higher undervoltage lockout (UVLO) hysteresis of the UCC2813-2 and UCC2813-4 make these ideal choices for use in off-line power supplies.

The UCC2813-x series is specified for the automotive temperature range of -40°C to 125°C.

PART NUMBER	MAXIMUM DUTY CYCLE	REFERENCE VOLTAGE	TURN-ON THRESHOLD	TURN-OFF THRESHOLD
UCC2813-0	100%	5 V	7.2 V	6.9 V
UCC2813-1	50%	5 V	9.4 V	7.4 V
UCC2813-2	100%	5 V	12.5 V	8.3 V
UCC2813-3	100%	4 V	4.1 V	3.6 V
UCC2813-4	50%	5 V	12.5 V	8.3 V
UCC2813-5	50%	4 V	4.1 V	3.6 V



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PRODUCTION DATA information is current as of publication date. Products conform to specifications per the terms of Texas Instruments standard warranty. Production processing does not necessarily include testing of all parameters.



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## block diagram



#### AVAILABLE OPTIONS<sup>†‡</sup>



- <sup>†</sup> For the most current package and ordering information, see the Package Option Addendum at the end of this document, or see the TI web site at www.ti.com.
- <sup>‡</sup> Package drawings, thermal data, and symbolization are available at www.ti.com/packaging.

D PACKAGE (TOP VIEW)









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absolute maximum ratings over operating free-air temperature range (unless otherwise noted)<sup>†‡</sup>

V <sub>CC</sub> voltage §	12 V
V <sub>CC</sub> current §	30 mA
Output current, I <sub>O</sub>	±1 A
Output energy (capacitive load)	20 μJ
Analog inputs (FB, CS)	. –0.3 V to 6.3 V
Power dissipation at $T_A < +25^{\circ}C$ (D package)	0.65 W
Storage temperature range, T <sub>stg</sub>	$-65^{\circ}C$ to $150^{\circ}C$
Lead temperature soldering 1,6 mm (1/16 inch) from case for 10 seconds	300°C

<sup>†</sup> Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

<sup>‡</sup>Unless otherwise indicated, voltages are reference to ground and currents are positive into and negative out of the specified terminals.

§ In normal operation V<sub>CC</sub> is powered through a current limiting resistor. Absolute maximum of 12 V applies when V<sub>CC</sub> is driven from a low impedance source such that I<sub>CC</sub> does not exceed 30 mA (which includes gate drive current requirement).

# electrical characteristics $T_A = -40^{\circ}$ C to $125^{\circ}$ C, $V_{CC} = 10$ V (see Note 1), RT = 100 k $\Omega$ from REF to RC, CT = 330 pF from RC to GND, 0.1-F capacitor from $V_{CC}$ to GND, 0.1-F capacitor from $V_{REF}$ to GND, and $T_A = T_J$ (unless otherwise noted)

PARAMETER	TEST CO	MIN	TYP	MAX	UNIT	
Reference Section						
Output up home	T 05°0 1 00 1	UCC2813-0/-1/-2/-4	4.925	5	5.075	V
Output voltage	$T_{J} = 25^{\circ}C, I = 0.2 \text{ mA}$	UCC2813-3/-5	3.94	4	4.06	V
Load regulation voltage	I = 0.2 mA to 5 mA		10	30	mV	
Total confection confection	On a Nata E	UCC2813-0/-1/-2/-4	4.84	5	5.1	
Total variation voltage	See Note 5	UCC2813-3/-5	3.84	4	4.08	V
Output noise voltage	f = 10 Hz to 10 kHz, See Note 7	TJ = 25°C		70		μV
Long term stability	1000 hours, See Note 7	T <sub>A</sub> = 125°C		5		mV
Output short-circuit current			-5		-35	mA



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# electrical characteristics $T_A = -40^{\circ}$ C to $125^{\circ}$ C, $V_{CC} = 10$ V (see Note 1), RT = 100 k $\Omega$ from REF to RC, CT = 330 pF from RC to GND, 0.1 F capacitor from $V_{CC}$ to GND, 0.1 F capacitor from $V_{REF}$ to GND and $T_A = T_J$ (unless otherwise noted)

PARAMETER	TEST CONDITIONS			ТҮР	MAX	UNIT
Oscillator Section	1		•			
		UCC2813-0/-1/-2/-4	40	46	52	
Oscillator frequency	See Note 2	UCC2813-3/-5	26	31	36	kHz
Temperature stability	See Note 7			2.5		%
Amplitude, peak to peak			2.25	2.4	2.55	V
Oscillator peak voltage				2.45		V
Error Amplifier Section						
	COMP = 2.5 V	UCC2813-0/-1/-2/-4	2.42	2.5	2.56	v
	COMP = 2.0 V	UCC2813-3/-5	1.92	2	2.05	v
Input bias current			-2		2	μA
Open loop voltage gain			60	80		dB
COMP sink current	FB = 2.7 V, COMP =	1.1 V	0.3		3.5	mA
COMP source current	FB = 1.8 V, COMP =	REF – 1.2 V	-0.2	-0.5	-0.8	mA
Gain bandwidth product	See Note 7			2		MHz
PWM Section						
		UCC2813-0/-2/-3	97	99	100	0/
		UCC2813-1/-4/-5	48	49	50	%
Minimum duty cycle	COMP = 0 V				0	%
Current Sense Section						
Gain	See Note 3		1.1	1.65	1.8	V/V
Maximum input signal	COMP = 5 V, See Note	4	0.9	1	1.1	V
Input bias current			-200		200	nA
CS blank time			50	100	150	ns
Over-current threshold voltage			1.32	1.55	1.7	V
COMP to CS offset voltage	CS = 0 V		0.45	0.9	1.35	V
Output Section (OUT)						
	I <sub>OUT</sub> = 20 mA	All parts		0.1	0.4	
	I <sub>OUT</sub> = 200 mA	All parts		0.35	0.9	V
Low-level output voltage	$I_{OUT} = 50 \text{ mA}, V_{CC} = 5 \text{ V}$	UCC2813-3/-5	313-3/-5 0.15		0.4	v
	I <sub>OUT</sub> = 20 mA, V <sub>CC</sub> = 0 V	All parts		0.7	1.2	
	I <sub>OUT</sub> = -20 mA	All parts		0.15	0.4	
High-level output voltage, V <sub>SAT</sub> (V <sub>CC</sub> – OUT)	I <sub>OUT</sub> = -200 mA	All parts		1	1.9	V
	$I_{OUT} = -50 \text{ mA}, V_{CC} = 5 \text{ V}$	UCC2813-3/-5		0.4	0.9	
Rise time	C <sub>L</sub> = 1 nF			41	70	ns
Fall time	C <sub>L</sub> = 1 nF			44	75	ns



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# electrical characteristics $T_A = -40^{\circ}$ C to $125^{\circ}$ C, $V_{CC} = 10$ V (see Note 1), RT = 100 k $\Omega$ from REF to RC, CT = 330 pF from RC to GND, 0.1 F capacitor from $V_{CC}$ to GND, 0.1 F capacitor from $V_{REF}$ to GND, and $T_A = T_J$ (unless otherwise noted)

PARAMETER	-	TEST CONDITIONS			ТҮР	MAX	UNIT
Undervoltage Lockout Section							
			UCC2813-0	6.6	7.2	7.8	
Otherst these shared	Or a Nation O		UCC2813-1	8.6	9.4	10.2	
Start threshold	See Note 6		UCC2813-2/-4	11.5	12.5	13.5	V
			UCC2813-3/-5	3.7	4.1	4.5	
			UCC2813-0	6.3	6.9	7.5	
			UCC2813-1	6.8	7.4	8	
Stop threshold	See Note 6		UCC2813-2/-4	7.6	8.3	9	
			UCC2813-3/-5	3.2	3.6	4	
			UCC2813-0	0.12	0.3	0.48	
			UCC2813-1	1.6	2	2.4	
Start to stop hysteresis			UCC2813-2/-4	3.5	4.2	5.1	V
			UCC2813-3/-5	0.2	0.5	0.8	
Soft-Start Section							
COMP rise time	FB = 1.8 V,	Rise from	0.5 V to REF – 1 V		4	10	ms
Overall							
Start-up current	V <sub>CC</sub> < Start hree	V <sub>CC</sub> < Start hreshold			0.1	0.23	mA
Operating supply current	FB = 0 V,	CS = 0 V,	RC = 0 V		0.5	1.2	mA
V <sub>CC</sub> internal zener voltage	I <sub>CC</sub> = 10 mA,	See Notes	6 and 8	12	13.5	15	V
V <sub>CC</sub> internal zener voltage minus start	See Note 6		UCC2813-2/-4	0.5	1.0		V

NOTES: 1. Adjust V<sub>CC</sub> above the start threshold before setting at 10 V.

 Oscillator frequency for the UCC2813-0, UCC2813-2, and UCC2813-3 is the output frequency. Oscillator frequency for the UCC2813-1, UCC2813-4, and UCC2813-5 is twice the output frequency.
 Gain is defined by: ΔV<sub>COMP</sub> 0 ≤ V<sub>CS</sub> ≤ 0.8 V.

Gain is defined by: 
$$A = \frac{\Delta V_{COMP}}{\Delta V_{CS}}$$
  $0 \le V_{CS} \le 0.8 \text{ V}.$ 

4. Parameter measured at trip point of latch with pin 2 at 0 V.

5. Total variation includes temperature stability and load regulation.

6. Start threshold, stop threshold, and Zener shunt thresholds track one another.

7. Not production tested

8. The device is fully operating in clamp mode as the forcing current is higher than the normal operating supply current.



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### detailed terminal descriptions

#### COMP

COMP is the output of the error amplifier and the input of the PWM comparator.

Unlike other devices, the error amplifier in the UCC2813 family is a true, low output-impedance, 2-MHz operational amplifier. As such, the COMP terminal can both source and sink current. However, the error amplifier is internally current limited, so that one can command zero duty cycle by externally forcing COMP to GND.

The UCC2813 family features built-in full-cycle soft start. Soft start is implemented as a clamp on the maximum COMP voltage.

#### CS

CS is the input to the current sense comparators. The UCC2813 family has two different current sense comparators: the PWM comparator and an overcurrent comparator.

The UCC2813 family contains digital current sense filtering, which disconnects the CS terminal from the current sense comparator during the 100 ns interval immediately following the rising edge of the OUT pin. This digital filtering, also called leading-edge blanking, means that in most applications, no analog filtering (RC filter) is required on CS. Compared to an external RC filter technique, the leading-edge blanking provides a smaller effective CS to OUT propagation delay. Note, however, that the minimum non-zero on time of the OUT signal is directly affected by the leading-edge blanking and the CS to OUT propagation delay.

The overcurrent comparator is only intended for fault sensing, and exceeding the overcurrent threshold causes a soft start cycle.

#### FB

FB is the inverting input of the error amplifier. For best stability, keep FB lead length as short as possible and FB stray capacitance as small as possible.

### GND

GND is reference ground and power ground for all functions on this part.

### OUT

OUT is the output of a high-current power driver capable of driving the gate of a power MOSFET with peak currents exceeding  $\pm$  750 mA. OUT is actively held low when V<sub>CC</sub> is below the UVLO threshold.

The high-current power driver consists of FET output devices, which can switch all of the way to GND and all of the way to  $V_{CC}$ . The output stage also provides a low impedance to overshoot and undershoot. This means that, in many cases, external Schottky clamp diodes are not required.



## detailed descriptions (continued)

#### RC

RC is the oscillator timing pin. For fixed frequency operation, set timing capacitor charging current by connecting a resistor from REF to RC. Set frequency by connecting timing capacitor from RC to GND. For best perfomance, keep the timing capacitor lead to GND as short and direct as possible. If possible, use separate ground traces for the timing capacitor and all other functions.

The frequency of oscillation can be estimated with the following equations:

UCC2813-0/1/2/4 : 
$$F = \frac{1.5}{R \times C}$$
  
UCC2813-3/UCC2813-5 :  $F = \frac{1.0}{R \times C}$ 

(1)

where frequency is in Hz, resistance is in ohms, and capacitance is in farads. The recommended range of the timing resistors is between 10 k $\Omega$  and 200 k $\Omega$  and the timing capacitor is 100 pF to 1000 pF. Never use a timing resistor less than 10 k.

To prevent noise problems, bypass  $V_{CC}$  to GND with a ceramic capacitor as close to the  $V_{CC}$  pin as possible. An electrolytic capacitor may also be used in addition to the ceramic capacitor.

#### voltage reference (REF)

REF is the voltage reference for the error amplifier and also for many other functions on the IC. REF is also used as the logic power supply for high-speed switching logic on the IC.

When  $V_{CC}$  is greater than 1 V and less than the UVLO threshold, REF is pulled to ground through a 5-k $\Omega$  resistor. This means that REF can be used as a logic output indicating power system status. It is important for reference stability that REF is bypassed to GND with a ceramic capacitor as close to the pin as possible. An electrolytic capacitor may also be used in addition to the ceramic capacitor. A minimum of 0.1- $\mu$ F ceramic capacitor is required. Additional REF bypassing is required for external loads greater than 2.5 mA on the reference.

To prevent noise problems with high-speed switching transients, bypass REF to ground with a ceramic capacitor close to the IC package.

### power (V<sub>CC</sub>)

 $V_{CC}$  is the power input connection for this device. In normal operation,  $V_{CC}$  is powered through a current-limiting resistor. Although quiescent  $V_{CC}$  current is low, total supply current will be higher, depending on OUT current. Total  $V_{CC}$  current is the sum of quiescent  $V_{CC}$  current and the average OUT current. Knowing the operating frequency and the MOSFET gate charge (Q<sub>q</sub>), average OUT current can be calculated from:

 $\mathsf{I}_{\mathsf{OUT}} = \mathsf{Q}_{\mathsf{g}} \times \mathsf{F}.$ 

(2)



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## PARAMETER MEASUREMENT INFORMATION

80

60

40

20

0

-20

1k

10k

Gain (dB)



The UCC2813-0/-1/-2/-3/-4/-5 oscillator generates a sawtooth waveform on RC. The rise time is set by the time constant of RT and CT. The fall time is set by CT and an internal transistor on-resistance of approximately 125. During the fall time, the output is off and the maximum duty cycle is reduced below 50% or 100% depending on the part number. Larger timing capacitors increase the discharge time and reduce the maximum duty cycle and frequency.







UCC2813-0/1/2/4 Oscillator Frequency

1**M** 

100k

Frequency (Hz)

Figure 2

Error Amplifier

**Gain/Phase Response** 

Phase

Gain

135

90 0

45

0

10M

Phase



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Figure 9





Figure 11





## PACKAGING INFORMATION

Orderable Device	Status	Package Type	Package	Pins	Package Qty	Eco Plan	Lead/Ball Finish	MSL Peak Temp	Op Temp (°C)	Top-Side Markings	Samples
	(1)		Drawing			(2)		(3)		(4)	
UCC2813QDR-0Q1	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 125	2813-0Q1	Samples
UCC2813QDR-1Q1	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 125	2813-1Q1	Samples
UCC2813QDR-2Q1	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 125	2813-2Q1	Samples
UCC2813QDR-3Q1	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 125	2813-3Q1	Samples
UCC2813QDR-4Q1	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 125	2813-4Q1	Samples
UCC2813QDR-5Q1	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 125	2813-5Q1	Samples
UCC2813QPWR-3Q1	ACTIVE	TSSOP	PW	8	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 125	28133Q	Samples

<sup>(1)</sup> The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

**OBSOLETE:** TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.

**TBD:** The Pb-Free/Green conversion plan has not been defined.

**Pb-Free (RoHS):** TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes. **Pb-Free (RoHS Exempt):** This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between

the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

<sup>(3)</sup> MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

<sup>(4)</sup> Only one of markings shown within the brackets will appear on the physical device.



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24-Jan-2013

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#### OTHER QUALIFIED VERSIONS OF UCC2813-0-Q1, UCC2813-1-Q1, UCC2813-2-Q1, UCC2813-3-Q1, UCC2813-4-Q1, UCC2813-5-Q1 :

• Catalog: UCC2813-0, UCC2813-1, UCC2813-2, UCC2813-3, UCC2813-4, UCC2813-5

NOTE: Qualified Version Definitions:

• Catalog - TI's standard catalog product

# PACKAGE MATERIALS INFORMATION

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## TAPE AND REEL INFORMATION





## QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



*All dimensions are nomir	nal
---------------------------	-----

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
UCC2813QDR-3Q1	SOIC	D	8	2500	330.0	12.4	6.4	5.2	2.1	8.0	12.0	Q1

TEXAS INSTRUMENTS

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# PACKAGE MATERIALS INFORMATION

14-Mar-2013



\*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
UCC2813QDR-3Q1	SOIC	D	8	2500	367.0	367.0	35.0

D (R-PDSO-G8)

PLASTIC SMALL OUTLINE



NOTES: A. All linear dimensions are in inches (millimeters).

- B. This drawing is subject to change without notice.
- Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.006 (0,15) each side.
- Body width does not include interlead flash. Interlead flash shall not exceed 0.017 (0,43) each side.
- E. Reference JEDEC MS-012 variation AA.



PW (R-PDSO-G8)

PLASTIC SMALL OUTLINE



Α. All linear dimensions are in millimeters. Dimensioning and tolerancing per ASME Y14.5M-1994. Ŗ. This drawing is subject to change without notice.

🖄 Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0,15 each side.

Body width does not include interlead flash. Interlead flash shall not exceed 0,25 each side.

E. Falls within JEDEC MO-153



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Компания «ЭлектроПласт» предлагает заключение долгосрочных отношений при поставках импортных электронных компонентов на взаимовыгодных условиях!

Наши преимущества:

- Оперативные поставки широкого спектра электронных компонентов отечественного и импортного производства напрямую от производителей и с крупнейших мировых складов;
- Поставка более 17-ти миллионов наименований электронных компонентов;
- Поставка сложных, дефицитных, либо снятых с производства позиций;
- Оперативные сроки поставки под заказ (от 5 рабочих дней);
- Экспресс доставка в любую точку России;
- Техническая поддержка проекта, помощь в подборе аналогов, поставка прототипов;
- Система менеджмента качества сертифицирована по Международному стандарту ISO 9001;
- Лицензия ФСБ на осуществление работ с использованием сведений, составляющих государственную тайну;
- Поставка специализированных компонентов (Xilinx, Altera, Analog Devices, Intersil, Interpoint, Microsemi, Aeroflex, Peregrine, Syfer, Eurofarad, Texas Instrument, Miteq, Cobham, E2V, MA-COM, Hittite, Mini-Circuits, General Dynamics и др.);

Помимо этого, одним из направлений компании «ЭлектроПласт» является направление «Источники питания». Мы предлагаем Вам помощь Конструкторского отдела:

- Подбор оптимального решения, техническое обоснование при выборе компонента;
- Подбор аналогов;
- Консультации по применению компонента;
- Поставка образцов и прототипов;
- Техническая поддержка проекта;
- Защита от снятия компонента с производства.



#### Как с нами связаться

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